General Kit Information

FR-4

Epoxy-glass FR-4 is standard for most kits.

Polyimide (Optional)

For high temperatures during assembly or burn-in. Polymide Tg is 270˚C.

Copper Thickness

Usually 1.0 oz. of copper.

Hot Air Solder Leveling

Hot air solder leveling (HASL) during board fabrication gives boards a controlled plating flatness which assures coplanarity for fine pitch components.

Liquid Photo Imageable Solder Mask

Liquid photoimageable (LPI) soldermask does not interfere with solder paste screen printing.

X,Y Theta: (Accessory)

Component placement data for pick and place machines.

Gerber Data: (Accessory)

For solder paste stencil.

Lead-Free (Optional)

Available with white tin or electroless nickel.

Global Fiducials

A minimum of two global fiducials are located diagonally opposed as far apart as possible.

Local Fiducials

Used to locate the position of an individual component.

General

Kits are supplied with enough components for one side of the board only. Most boards are double sided.

OSP (Optional)

Organic Solder Preservative is available Special Order.

Standard Board Spec

Board Size: 5.5” x 4” (140mm x 100mm)

Layers: Double-sided

Board Material: FR4

Metalization: 1-ounce copper

Solder Mask: LPI (Liquid Photoimageable)

Silk Screen: White Ink

Tinning: HASL (Hot Air Solder Leveling)

Tooling Holes: .125” (3.18mm) 4-places

Stencil Information

In some cases, TopLine’s boards use 2-front sides, eliminating the need for separate “front” and “back” stencils.